

12-14-1998

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To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):

Hirofumi Ishida

Additional name(s) of conveying party(ies) attached? ☐ Yes ☒ No

3. Nature of conveyance:

☒ Assignment☐ Merger☐ Security Agreement☐ Change of Name☐ Other _____

Execution Date: _____

2. Name and address of receiving party(ies):

ELECTROPLATING ENGINEERS OF
JAPAN LIMITED

(A Japanese Corporation)

5-50, Shin-machi, Hiratsuka-shi
Kanagawa 254-0076 JapanAdditional name(s) & address(es) attached? ☐ Yes ☒ No

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the
application is: November 13, 1998

A. Patent Application No.(s)

B. Patent No.(s)

Additional numbers attached? ☐ Yes ☒ No5. Name and address of party to whom
correspondence concerning document should be
mailed:Kenneth Watov
WATOV & KIPNES, P.C.
P.O. Box 247
Princeton Junction, NJ 085506. Total number of applications and patents
involved: _____7. Total fee (37 CFR 3.41) \$ 40.00☒ Enclosed☒ Additional fees or credit for overpayment
should be charged to deposit account

8. Deposit account number:

23-0510

(Attach duplicate copy of this page if paying by deposit account)

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9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached
copy is a true copy of the original document.Kenneth Watov

Name of Person Signing

Kenneth Watov

Signature

December 3, 1998

Date

Total number of pages including cover sheet, attachments, and document: (2)

A S S I G N M E N T

For value received, I/we Hirofumi ISHIDA

residing respectively at 502, Atsugi Mouridai
Dai 3 Diamond Mansion, 1267-2, Hase, Atsugi-shi,
Kanagawa 243-0036 Japan

hereby sell, assign, and transfer to ELECTROPLATING ENGINEERS OF
JAPAN LIMITED

a corporation existing under the laws of Japan
located at 5-50, Shin-machi, Hiratsuka-shi, Kanagawa
254-0076 Japan

and its successors, assigns, and legal representatives, the entire right, title, and
interest for all countries including the United States of America, in and to
certain inventions relating to

CUP-TYPE PLATING METHOD AND CLEANING APPARATUS

USED THEREFOR

described in an application for Letters Patent of the United States,
executed by me/us on this date, and all patents which may be granted therefor, and
all divisions, reissues, continuations and extensions thereof, and authorize and
request the Commissioner of Patents and Trademarks to issue all patents on said
improvements or resulting therefrom to said Company as assignee of the entire
interest, and covenant that I/we have full right so to do, and agree that I/we will
communicate to said Company or its representatives any facts known to me/us
respecting said improvements and testify in any legal proceedings, sign all lawful
papers, execute all divisional, continuing and reissue applications, make all rightful
oaths and generally do everything possible to aid said Company, its successors,
assigns, and nominees, to obtain and enforce proper protection for said invention in
the United States.

Signature Hirofumi Ishida
Hirofumi ISHIDA

Date November 16, 1998

Signature _____

Date _____

Signature _____

Date _____

Signature _____

Date _____

Signature _____

Date _____ PATENT